

## SN74AUP2G14 Low-Power Dual Schmitt-Trigger Inverter

### 1 Features

- Available in the Texas Instruments NanoStar™ package
- Low static-power consumption ( $I_{CC} = 0.9\mu\text{A}$  maximum)
- Low dynamic-power consumption ( $C_{pd} = 4.3\text{pF}$  typical at 3.3V)
- Low input capacitance ( $C_i = 1.5\text{pF}$  typical)
- Low noise – overshoot and undershoot <math><10\%</math> of  $V_{CC}$
- $I_{off}$  supports partial-power-down mode operation
- Wide operating  $V_{CC}$  range of 0.8V to 3.6V
- Optimized for 3.3V operation
- 3.6V I/O tolerant to support mixed-mode signal Operation
- $t_{pd} = 4.3\text{ns}$  maximum at 3.3V
- Suitable for point-to-point applications
- Latch-up performance exceeds 100mA Per JESD 78, Class II
- ESD performance tested per JESD 22
  - 2000V human-body model (A114-B, Class II)
  - 1000V charged-device model (C101)

### 2 Applications

- Body control modules
- Engine control modules
- Servers and high-performance computing
- EPOS, ECR, and cash drawer
- Routers
- Desktop PC

### 3 Description

The AUP family is TI's premier solution to the industry's low-power needs in battery-powered portable applications. This family ensures a very low static- and dynamic-power consumption across the entire  $V_{CC}$  range of 0.8V to 3.6V, resulting in increased battery life (see [Figure 5-1](#)). This product also maintains excellent signal integrity (see the very low undershoot and overshoot characteristics shown in [Figure 5-2](#)).

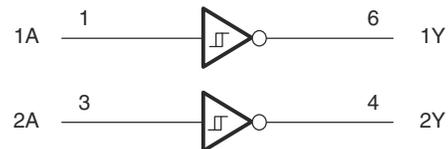
The SN74AUP2G14 contains two inverters and performs the Boolean function  $Y = \bar{A}$ . The device functions as two independent inverters, but because of Schmitt action, it may have different input threshold levels for positive-going ( $V_{T+}$ ) and negative-going ( $V_{T-}$ ) signals.

NanoStar™ package technology is a major breakthrough in IC packaging concepts, using the die as the package.

This device is fully specified for partial-power-down applications using  $I_{off}$ . The  $I_{off}$  circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

#### Device Information

PART NUMBER	PACKAGE	BODY SIZE (NOM)
SN74AUP2G14DCK	SC70 (6)	2.00mm × 1.25mm
SN74AUP2G14DRY	SON (6)	1.45mm × 1.00mm
SN74AUP2G14DSF	SON (6)	1.00mm × 1.00mm
SN74AUP2G14YFP	DSBGA (6)	1.00mm × 1.40mm



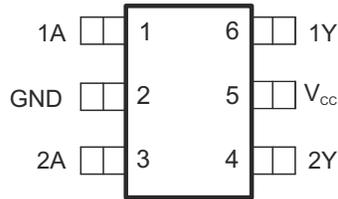
Logic Diagram (Positive Logic)



## Table of Contents

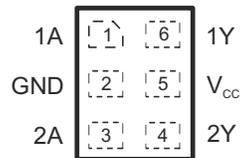
<b>1 Features</b> .....	<b>1</b>	<b>7 Detailed Description</b> .....	<b>13</b>
<b>2 Applications</b> .....	<b>1</b>	7.1 Overview.....	13
<b>3 Description</b> .....	<b>1</b>	7.2 Functional Block Diagram.....	13
<b>4 Pin Configuration and Functions</b> .....	<b>3</b>	7.3 Feature Description.....	13
<b>5 Specifications</b> .....	<b>4</b>	7.4 Device Functional Modes.....	13
5.1 Absolute Maximum Ratings.....	4	<b>8 Application and Implementation</b> .....	<b>14</b>
5.2 ESD Ratings.....	4	8.1 Application Information.....	14
5.3 Recommended Operating Conditions.....	5	8.2 Typical Application.....	14
5.4 Thermal Information.....	5	8.3 Power Supply Recommendations.....	15
5.5 Electrical Characteristics.....	6	8.4 Layout.....	15
5.6 Switching Characteristics.....	7	<b>9 Device and Documentation Support</b> .....	<b>17</b>
5.7 Switching Characteristics.....	7	9.1 Documentation Support.....	17
5.8 Switching Characteristics.....	7	9.2 Receiving Notification of Documentation Updates... 17	
5.9 Switching Characteristics.....	8	9.3 Support Resources.....	17
5.10 Operating Characteristics.....	8	9.4 Trademarks.....	17
5.11 Typical Characteristics.....	8	9.5 Electrostatic Discharge Caution.....	17
<b>6 Parameter Measurement Information</b> .....	<b>9</b>	9.6 Glossary.....	17
6.1 Propagation Delays, Setup and Hold Times, and Pulse Width.....	11	<b>10 Revision History</b> .....	<b>17</b>
6.2 Enable and Disable Times.....	12	<b>11 Mechanical, Packaging, and Orderable Information</b> .....	<b>18</b>

## 4 Pin Configuration and Functions

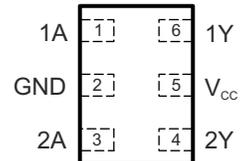


See mechanical drawings for dimensions.

**Figure 4-1. DCK Package 6-Pin SC70 Top View**



**Figure 4-2. DRY Package 6-Pin USON Top View**



**Figure 4-3. DSF Package 6-Pin X2SON Top View**



**Figure 4-4. YFP Package 6-Pin DSBGA Top View**

**Table 4-1. Pin Functions**

NAME	PIN				I/O	DESCRIPTION
	DCK	DRY	DSF	YFP		
1A	1	1	1	A1	I	Gate 1 logic signal
GND	2	2	2	B1	—	Ground
2A	3	3	3	C1	I	Gate 2 logic signal
1Y	6	6	6	A2	O	Gate 1 inverted signal
V <sub>CC</sub>	5	5	5	B2	—	Supply/Power Pin
2Y	4	4	4	C2	O	Gate 2 inverted signal

## 5 Specifications

### 5.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)<sup>(1)</sup>

		MIN	MAX	UNIT
V <sub>CC</sub>	Supply voltage	-0.5	4.6	V
V <sub>I</sub>	Input voltage <sup>(2)</sup>	-0.5	4.6	V
V <sub>O</sub>	Voltage range applied to any output in the high-impedance or power-off state <sup>(2)</sup>	-0.5	4.6	V
V <sub>O</sub>	Output voltage range in the high or low state <sup>(2)</sup>	-0.5	V <sub>CC</sub> + 0.5	V
I <sub>IK</sub>	Input clamp current	V <sub>I</sub> < 0	-50	mA
I <sub>OK</sub>	Output clamp current	V <sub>O</sub> < 0	-50	mA
I <sub>O</sub>	Continuous output current		±20	mA
	Continuous current through V <sub>CC</sub> or GND		±50	mA
T <sub>stg</sub>	Storage temperature	-65	150	°C

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.

### 5.2 ESD Ratings

		VALUE	UNIT
V <sub>(ESD)</sub>	Electrostatic discharge	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 <sup>(1)</sup>	±2000
		Charged-device model (CDM), per JEDEC specification JESD22-C101 <sup>(2)</sup>	±1000

- (1) JEDEC document JEP155 states that 500V HBM allows safe manufacturing with a standard ESD control process.
- (2) JEDEC document JEP157 states that 250V CDM allows safe manufacturing with a standard ESD control process.

### 5.3 Recommended Operating Conditions

See (1)

		MIN	MAX	UNIT
V <sub>CC</sub>	Supply voltage	0.8	3.6	V
V <sub>I</sub>	Input voltage	0	3.6	V
V <sub>O</sub>	Output voltage	0	V <sub>CC</sub>	V
I <sub>OH</sub>	High-level output current	V <sub>CC</sub> = 0.8V	-20	μA
		V <sub>CC</sub> = 1.1V	-1.1	mA
		V <sub>CC</sub> = 1.4V	-1.7	
		V <sub>CC</sub> = 1.65V	-1.9	
		V <sub>CC</sub> = 2.3V	-3.1	
		V <sub>CC</sub> = 3V	-4	
I <sub>OL</sub>	Low-level output current	V <sub>CC</sub> = 0.8V	20	μA
		V <sub>CC</sub> = 1.1V	1.1	mA
		V <sub>CC</sub> = 1.4V	1.7	
		V <sub>CC</sub> = 1.65V	1.9	
		V <sub>CC</sub> = 2.3V	3.1	
		V <sub>CC</sub> = 3V	4	
T <sub>A</sub>	Operating free-air temperature	-40	85	°C

(1) All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. See [Implications of Slow or Floating CMOS Inputs](#).

### 5.4 Thermal Information

THERMAL METRIC <sup>(1)</sup>	SN74AUP2G14				UNIT	
	DRY (SON)	DSF (SON)	YFP (DSBGA)	DCK (SC70)		
	PINS	PINS	PINS	PINS		
R <sub>θJA</sub>	Junction-to-ambient thermal resistance	234	300	132	252	°C/W

(1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics](#) application report.

## 5.5 Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V <sub>CC</sub>	T <sub>A</sub> = 25°C			T <sub>A</sub> = –40°C to 85°C		UNIT
			MIN	TYP	MAX	MIN	MAX	
V <sub>T+</sub> Positive-going input threshold voltage		0.8V	0.3		0.6	0.3	0.6	V
		1.1V	0.53		0.9	0.53	0.9	
		1.4V	0.74		1.11	0.74	1.11	
		1.65V	0.91		1.29	0.91	1.29	
		2.3V	1.37		1.77	1.37	1.77	
		3V	1.88		2.29	1.88	2.29	
V <sub>T–</sub> Negative-going input threshold voltage		0.8V	0.1		0.6	0.1	0.6	V
		1.1V	0.26		0.65	0.26	0.65	
		1.4V	0.39		0.75	0.39	0.75	
		1.65V	0.47		0.84	0.47	0.84	
		2.3V	0.69		1.04	0.69	1.04	
		3V	0.88		1.24	0.88	1.24	
ΔV <sub>T</sub> Hysteresis (V <sub>T+</sub> – V <sub>T–</sub> )		0.8V	0.07		0.5	0.07	0.5	V
		1.1V	0.08		0.46	0.08	0.46	
		1.4V	0.18		0.56	0.18	0.56	
		1.65V	0.27		0.66	0.27	0.66	
		2.3V	0.53		0.92	0.53	0.92	
		3V	0.79		1.31	0.79	1.31	
V <sub>OH</sub>	I <sub>OH</sub> = –20μA	0.8V to 3.6V	V <sub>CC</sub> – 0.1		V <sub>CC</sub> – 0.1		V	
	I <sub>OH</sub> = –1.1mA	1.1V	0.75 × V <sub>CC</sub>		0.7 × V <sub>CC</sub>			
	I <sub>OH</sub> = –1.7mA	1.4V	1.11		1.03			
	I <sub>OH</sub> = –1.9mA	1.65V	1.32		1.3			
	I <sub>OH</sub> = –2.3mA	2.3V	2.05		1.97			
	I <sub>OH</sub> = –3.1mA		1.9		1.85			
	I <sub>OH</sub> = –2.7mA	3V	2.72		2.67			
	I <sub>OH</sub> = –4mA		2.6		2.55			
V <sub>OL</sub>	I <sub>OL</sub> = 20μA	0.8 V to 3.6V			0.1	0.1	V	
	I <sub>OL</sub> = 1.1mA	1.1V			0.3 × V <sub>CC</sub>	0.3 × V <sub>CC</sub>		
	I <sub>OL</sub> = 1.7mA	1.4V			0.31	0.37		
	I <sub>OL</sub> = 1.9mA	1.65V			0.31	0.35		
	I <sub>OL</sub> = 2.3mA	2.3V			0.31	0.33		
	I <sub>OL</sub> = 3.1mA				0.44	0.45		
	I <sub>OL</sub> = 2.7mA	3V			0.31	0.33		
	I <sub>OL</sub> = 4mA				0.44	0.45		
I <sub>I</sub>	A or B input	V <sub>I</sub> = GND to 3.6V	0V to 3.6V		0.1	0.5	μA	
I <sub>off</sub>		V <sub>I</sub> or V <sub>O</sub> = 0V to 3.6V	0V		0.2	0.6	μA	
ΔI <sub>off</sub>		V <sub>I</sub> or V <sub>O</sub> = 0V to 3.6V	0V to 0.2V		0.2	0.6	μA	
I <sub>CC</sub>		V <sub>I</sub> = GND or (V <sub>CC</sub> to 3.6V), I <sub>O</sub> = 0	0.8V to 3.6V		0.5	0.9	μA	
ΔI <sub>CC</sub>		V <sub>I</sub> = V <sub>CC</sub> – 0.6V <sup>(1)</sup> , I <sub>O</sub> = 0	3.3V		40	50	μA	
C <sub>i</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND	0V	1.5				pF	
		3.6V	1.5					
C <sub>o</sub>	V <sub>O</sub> = GND	0V	3				pF	

(1) One input at V<sub>CC</sub> – 0.6V, other input at V<sub>CC</sub> or GND.

## 5.6 Switching Characteristics

over recommended operating free-air temperature range, Switching Characteristics:  $C_L = 5\text{pF}$  (unless otherwise noted) (see Figure 6-3 and Figure 6-4)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC}$	$T_A = 25^\circ\text{C}$			$T_A = -40^\circ\text{C to } 85^\circ\text{C}$		UNIT
				MIN	TYP	MAX	MIN	MAX	
$t_{pd}$	A	Y	0.8V		18				ns
			$1.2\text{V} \pm 0.1\text{V}$	2.6	7.3	12.8	2.1	15.6	
			$1.5\text{V} \pm 0.1\text{V}$	1.4	5.2	8.7	0.9	10.3	
			$1.8\text{V} \pm 0.15\text{V}$	1	4.2	6.6	0.5	8.2	
			$2.5\text{V} \pm 0.2\text{V}$	1	3	4.4	0.5	5.5	
			$3.3\text{V} \pm 0.3\text{V}$	1	2.4	3.5	0.5	4.3	

## 5.7 Switching Characteristics

over recommended operating free-air temperature range, Switching Characteristics  $C_L = 10\text{pF}$  (unless otherwise noted) (see Figure 6-3 and Figure 6-4)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC}$	$T_A = 25^\circ\text{C}$			$T_A = -40^\circ\text{C to } 85^\circ\text{C}$		UNIT
				MIN	TYP	MAX	MIN	MAX	
$t_{pd}$	A	Y	0.8V		18.4				ns
			$1.2\text{V} \pm 0.1\text{V}$	4.6	7.9	13.4	1.3	16.7	
			$1.5\text{V} \pm 0.1\text{V}$	4	6	9.6	2.2	11.8	
			$1.8\text{V} \pm 0.15\text{V}$	3.6	5	7.9	2.4	9.5	
			$2.5\text{V} \pm 0.2\text{V}$	3.2	4	5.5	2.3	6.8	
			$3.3\text{V} \pm 0.3\text{V}$	2.9	3.5	4.6	2.1	5.6	

## 5.8 Switching Characteristics

over recommended operating free-air temperature range, Switching Characteristics  $C_L = 15\text{pF}$  (unless otherwise noted) (see Figure 6-3 and Figure 6-4)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC}$	$T_A = 25^\circ\text{C}$			$T_A = -40^\circ\text{C to } 85^\circ\text{C}$		UNIT
				MIN	TYP	MAX	MIN	MAX	
$t_{pd}$	A	Y	0.8V		24				ns
			$1.2\text{V} \pm 0.1\text{V}$	3.6	9.9	16.3	3.1	19.9	
			$1.5\text{V} \pm 0.1\text{V}$	2.3	7.2	11.1	1.8	13.2	
			$1.8\text{V} \pm 0.15\text{V}$	1.6	5.8	8.7	1.1	10.6	
			$2.5\text{V} \pm 0.2\text{V}$	1	4.3	5.9	0.5	7.3	
			$3.3\text{V} \pm 0.3\text{V}$	1	3.4	4.8	0.5	5.9	

### 5.9 Switching Characteristics

over recommended operating free-air temperature range, Switching Characteristics  $C_L = 30\text{pF}$  (unless otherwise noted) (see Figure 6-3 and Figure 6-4)

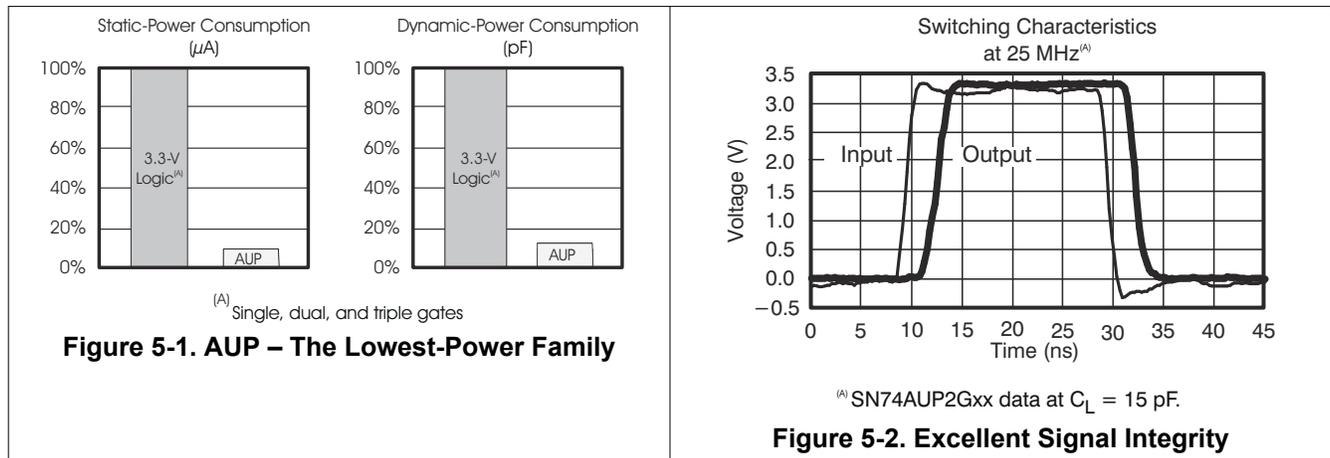
PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC}$	$T_A = 25^\circ\text{C}$			$T_A = -40^\circ\text{C to } 85^\circ\text{C}$		UNIT
				MIN	TYP	MAX	MIN	MAX	
$t_{pd}$	A	Y	0.8V		32.8				ns
			$1.2\text{V} \pm 0.1\text{V}$	4.9	13.1	20.9	4.4	25.5	
			$1.5\text{V} \pm 0.1\text{V}$	3.4	9.5	14.2	2.9	16.9	
			$1.8\text{V} \pm 0.15\text{V}$	2.5	7.7	11	2	13.5	
			$2.5\text{V} \pm 0.2\text{V}$	1.8	5.7	7.6	1.3	9.4	
			$3.3\text{V} \pm 0.3\text{V}$	1.5	4.7	6.2	1	7.5	

### 5.10 Operating Characteristics

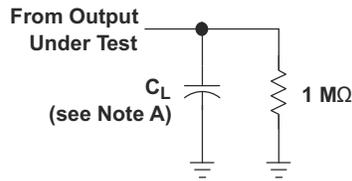
$T_A = 25^\circ\text{C}$

PARAMETER	TEST CONDITIONS	$V_{CC}$	TYP	UNIT
$C_{pd}$ Power dissipation capacitance	$f = 10\text{MHz}$	0.8V	4	pF
		$1.2\text{V} \pm 0.1\text{V}$	4	
		$1.5\text{V} \pm 0.1\text{V}$	4	
		$1.8\text{V} \pm 0.15\text{V}$	4	
		$2.5\text{V} \pm 0.2\text{V}$	4.1	
		$3.3\text{V} \pm 0.3\text{V}$	4.3	

### 5.11 Typical Characteristics

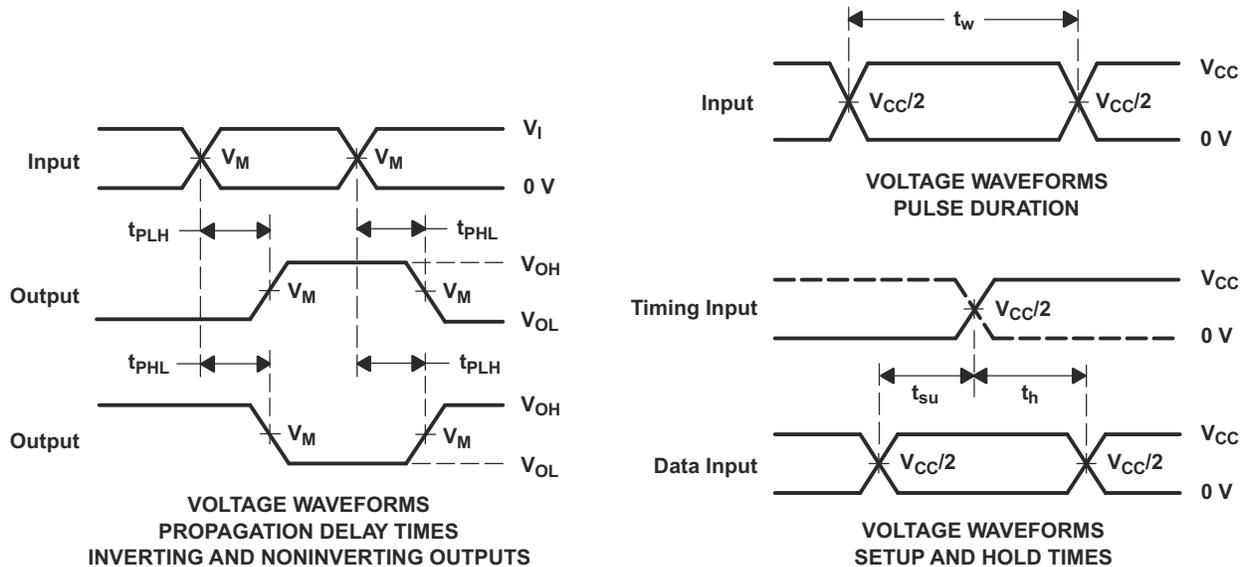


## 6 Parameter Measurement Information



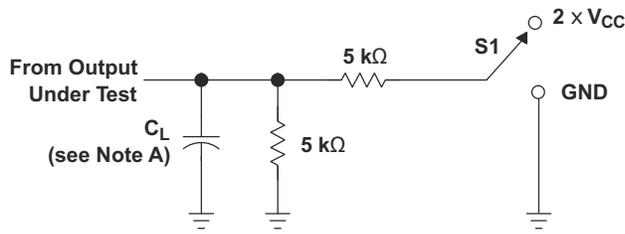
LOAD CIRCUIT

	$V_{CC} = 0.8 \text{ V}$	$V_{CC} = 1.2 \text{ V}$ $\pm 0.1 \text{ V}$	$V_{CC} = 1.5 \text{ V}$ $\pm 0.1 \text{ V}$	$V_{CC} = 1.8 \text{ V}$ $\pm 0.15 \text{ V}$	$V_{CC} = 2.5 \text{ V}$ $\pm 0.2 \text{ V}$	$V_{CC} = 3.3 \text{ V}$ $\pm 0.3 \text{ V}$
$C_L$	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF
$V_M$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$
$V_I$	$V_{CC}$	$V_{CC}$	$V_{CC}$	$V_{CC}$	$V_{CC}$	$V_{CC}$



- A.  $C_L$  includes probe and jig capacitance.
- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 10\text{MHz}$ ,  $Z_O = 50\Omega$ , for propagation delays  $t_r/t_f = 3\text{ns}$ , for setup and hold times and pulse width  $t_r/t_f = 1.2\text{ns}$ .
- D. The outputs are measured one at a time, with one transition per measurement.
- E.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .
- F. All parameters and waveforms are not applicable to all devices.

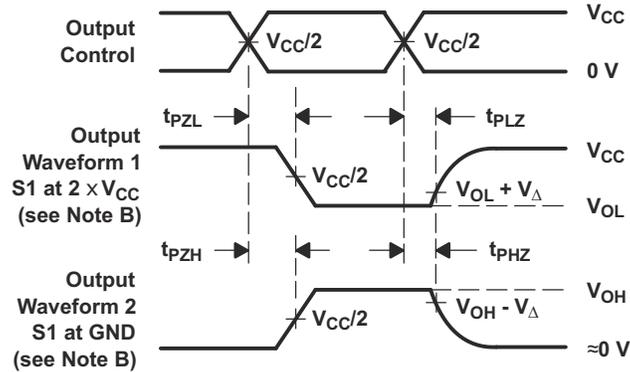
Figure 6-1. Load Circuit and Voltage Waveforms



TEST	S1
$t_{PLZ}/t_{PZL}$	$2 \times V_{CC}$
$t_{PHZ}/t_{PHL}$	GND

LOAD CIRCUIT

	$V_{CC} = 0.8 \text{ V}$	$V_{CC} = 1.2 \text{ V}$ $\pm 0.1 \text{ V}$	$V_{CC} = 1.5 \text{ V}$ $\pm 0.1 \text{ V}$	$V_{CC} = 1.8 \text{ V}$ $\pm 0.15 \text{ V}$	$V_{CC} = 2.5 \text{ V}$ $\pm 0.2 \text{ V}$	$V_{CC} = 3.3 \text{ V}$ $\pm 0.3 \text{ V}$
$C_L$	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF
$V_M$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$
$V_I$	$V_{CC}$	$V_{CC}$	$V_{CC}$	$V_{CC}$	$V_{CC}$	$V_{CC}$
$V_{\Delta}$	0.1 V	0.1 V	0.1 V	0.15 V	0.15 V	0.3 V

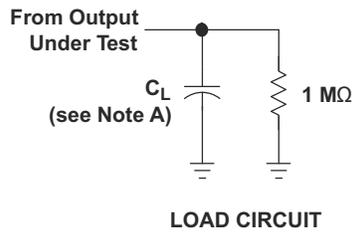


VOLTAGE WAVEFORMS  
ENABLE AND DISABLE TIMES  
LOW- AND HIGH-LEVEL ENABLING

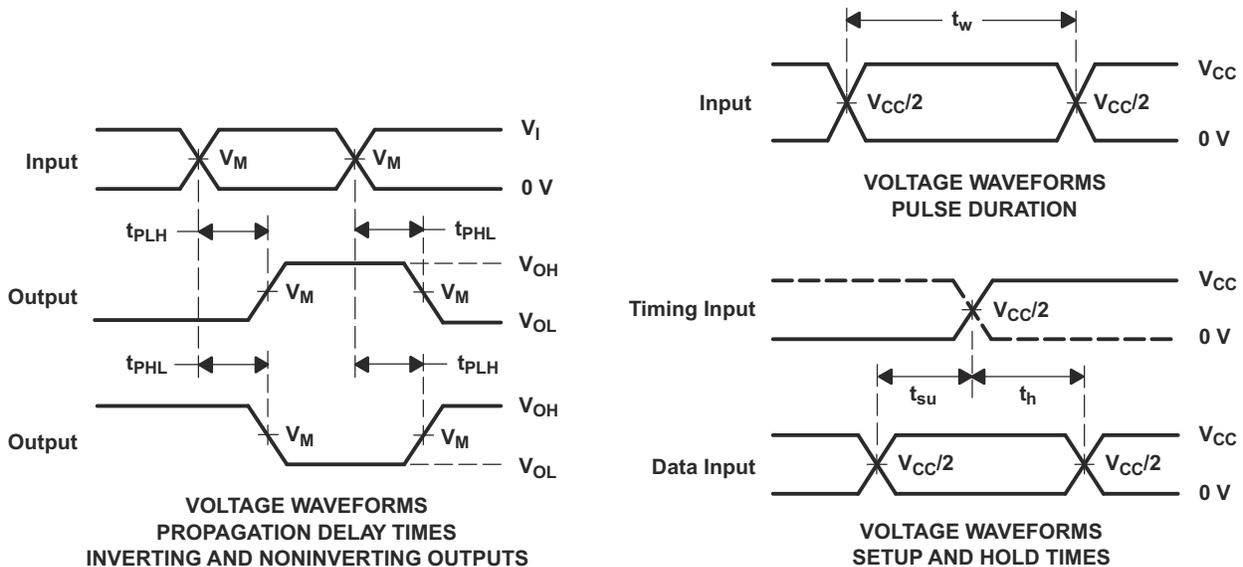
- A.  $C_L$  includes probe and jig capacitance.
- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 10\text{MHz}$ ,  $Z_O = 50\Omega$ ,  $t_r/t_f = 3\text{ns}$ .
- D. The outputs are measured one at a time, with one transition per measurement.
- E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
- F.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .
- G. All parameters and waveforms are not applicable to all devices.

Figure 6-2. Load Circuit and Voltage Waveforms

### 6.1 Propagation Delays, Setup and Hold Times, and Pulse Width



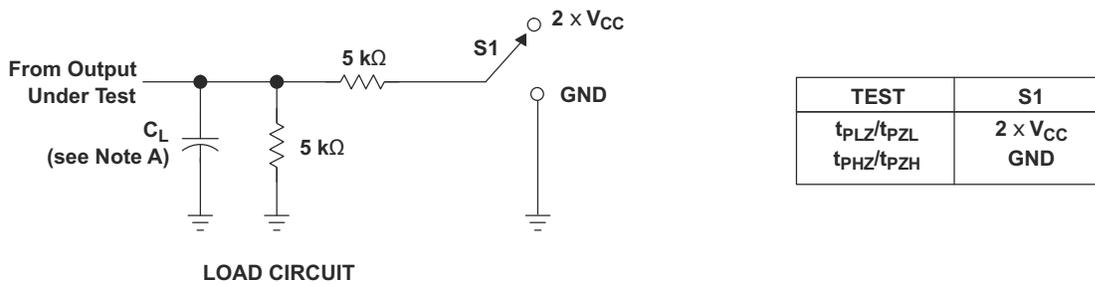
	$V_{CC} = 0.8 \text{ V}$	$V_{CC} = 1.2 \text{ V} \pm 0.1 \text{ V}$	$V_{CC} = 1.5 \text{ V} \pm 0.1 \text{ V}$	$V_{CC} = 1.8 \text{ V} \pm 0.15 \text{ V}$	$V_{CC} = 2.5 \text{ V} \pm 0.2 \text{ V}$	$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$
$C_L$	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF
$V_M$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$
$V_I$	$V_{CC}$	$V_{CC}$	$V_{CC}$	$V_{CC}$	$V_{CC}$	$V_{CC}$



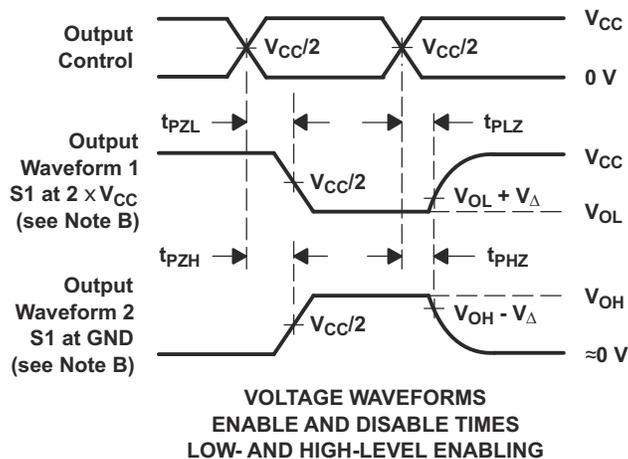
- A.  $C_L$  includes probe and jig capacitance.
- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 10 \text{ MHz}$ ,  $Z_O = 50 \Omega$ , for propagation delays  $t_r/t_f = 3 \text{ ns}$ , for setup and hold times and pulse width  $t_r/t_f = 1.2 \text{ ns}$ .
- D. The outputs are measured one at a time, with one transition per measurement.
- E.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .
- F. All parameters and waveforms are not applicable to all devices.

Figure 6-3. Load Circuit and Voltage Waveforms

## 6.2 Enable and Disable Times



	$V_{CC} = 0.8 \text{ V}$	$V_{CC} = 1.2 \text{ V}$ $\pm 0.1 \text{ V}$	$V_{CC} = 1.5 \text{ V}$ $\pm 0.1 \text{ V}$	$V_{CC} = 1.8 \text{ V}$ $\pm 0.15 \text{ V}$	$V_{CC} = 2.5 \text{ V}$ $\pm 0.2 \text{ V}$	$V_{CC} = 3.3 \text{ V}$ $\pm 0.3 \text{ V}$
$C_L$	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF
$V_M$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$
$V_I$	$V_{CC}$	$V_{CC}$	$V_{CC}$	$V_{CC}$	$V_{CC}$	$V_{CC}$
$V_{\Delta}$	0.1 V	0.1 V	0.1 V	0.15 V	0.15 V	0.3 V



- A.  $C_L$  includes probe and jig capacitance.
- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 10 \text{ MHz}$ ,  $Z_O = 50 \Omega$ ,  $t_r/t_f = 3 \text{ ns}$ .
- D. The outputs are measured one at a time, with one transition per measurement.
- E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
- F.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .
- G. All parameters and waveforms are not applicable to all devices.

**Figure 6-4. Load Circuit and Voltage Waveforms**

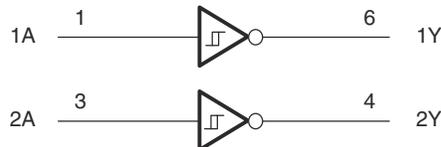
## 7 Detailed Description

### 7.1 Overview

The SN74AUP2G14 contains two inverters and performs the Boolean function  $Y = \overline{A}$ . The device functions as two independent inverters, but because of Schmitt action, it may have different input threshold levels for positive-going ( $V_{T+}$ ) and negative-going ( $V_{T-}$ ) signals.

This device is fully specified for partial-power-down applications using  $I_{off}$ . The  $I_{off}$  circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

### 7.2 Functional Block Diagram



**Figure 7-1. Logic Diagram (Positive Logic)**

### 7.3 Feature Description

As the inputs are 5.5V tolerant, the device can be used as a down translator. When the input voltage exceeds  $V_{T+}$  (Max), the output will follow VCC, performing down-translation if the input voltage exceeds VCC.

### 7.4 Device Functional Modes

[Table 7-1](#) lists the functional modes of SN74AUP2G14.

**Table 7-1. Function Table  
(Each Inverter)**

INPUT A	OUTPUT Y
H	L
L	H

## 8 Application and Implementation

### Note

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes, as well as validating and testing their design implementation to confirm system functionality.

### 8.1 Application Information

The SN74AUP2G14 contains two inverters and performs the Boolean function  $Y = \bar{A}$ . The device functions as two independent inverters, but because of Schmitt action, it may have different input threshold levels for positive-going ( $V_{T+}$ ) and negative-going ( $V_{T-}$ ) signals.

### 8.2 Typical Application

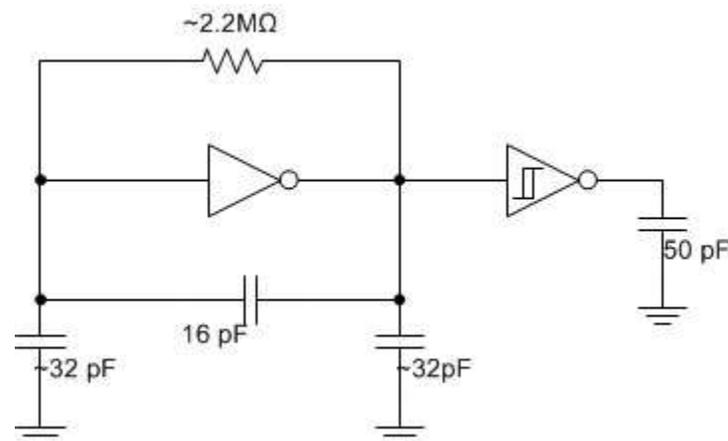


Figure 8-1. Typical Application Schematic

#### 8.2.1 Design Requirements

This device uses CMOS technology and has balanced output drive. Care should be taken to avoid bus contention because it can drive currents that would exceed maximum limits. The high drive will also create fast edges into light loads so routing and load conditions should be considered to prevent ringing.

#### 8.2.2 Detailed Design Procedure

##### 1. Recommended Input Conditions

- Rise time and fall time specs. See ( $\Delta t/\Delta V$ ) in the [Section 5.3](#) table.
- Specified high and low levels. See ( $V_{IH}$  and  $V_{IL}$ ) in the [Section 5.3](#) table.
- Inputs are overvoltage tolerant allowing them to go as high as ( $V_I$  max) in the [Section 5.3](#) table at any valid  $V_{CC}$ .

##### 2. Recommend Output Conditions

- Load currents should not exceed ( $I_O$  max) per output and should not exceed (continuous current through  $V_{CC}$  or GND) total current for the part. These limits are located in the [Section 5.1](#) table.
- Outputs should not be pulled above  $V_{CC}$ .

### 8.3 Power Supply Recommendations

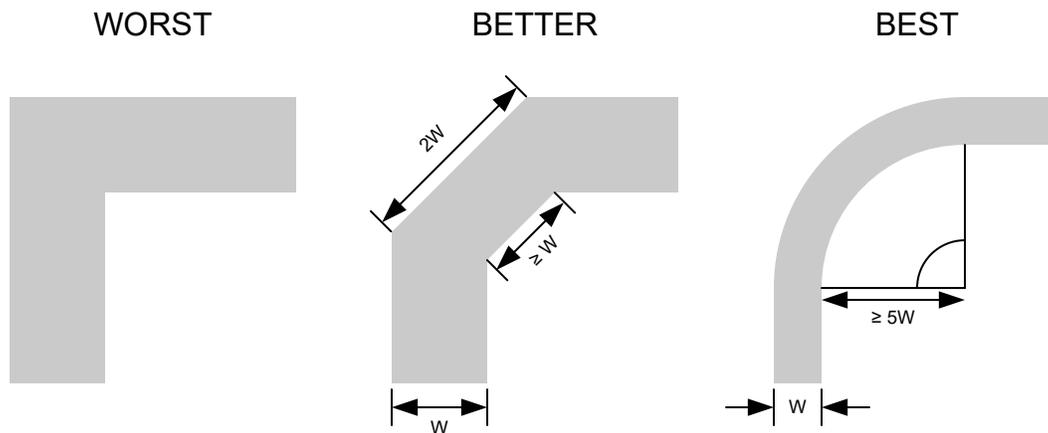
The power supply can be any voltage between the minimum and maximum supply voltage rating located in the table. Each VCC pin should have a good bypass capacitor to prevent power disturbance. For devices with a single supply, TI recommends a 0.1µF capacitor. If there are multiple VCC pins, then TI recommends a 0.01µF or 0.022µF capacitor for each power pin. It is ok to parallel multiple bypass capacitors to reject different frequencies of noise. 0.1µF and 1µF capacitors are commonly used in parallel. The bypass capacitor should be installed as close to the power pin as possible for best results.

### 8.4 Layout

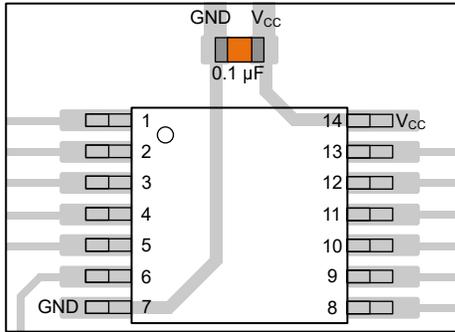
#### 8.4.1 Layout Guidelines

- Bypass capacitor placement
  - Place near the positive supply terminal of the device
  - Provide an electrically short ground return path
  - Use wide traces to minimize impedance
  - Keep the device, capacitors, and traces on the same side of the board whenever possible
- Signal trace geometry
  - 8mil to 12mil trace width
  - Lengths less than 12cm to minimize transmission line effects
  - Avoid 90° corners for signal traces
  - Use an unbroken ground plane below signal traces
  - Flood fill areas around signal traces with ground
  - Parallel traces must be separated by at least 3x dielectric thickness
  - For traces longer than 12cm
    - Use impedance controlled traces
    - Source-terminate using a series damping resistor near the output
    - Avoid branches; buffer each signal that must branch separately

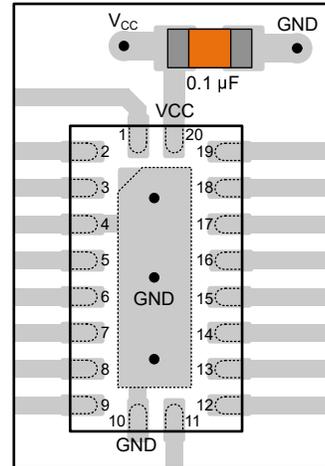
#### 8.4.2 Layout Example



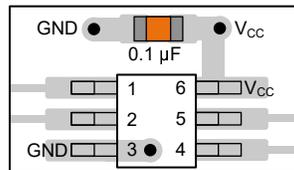
**Figure 8-2. Example Trace Corners for Improved Signal Integrity**



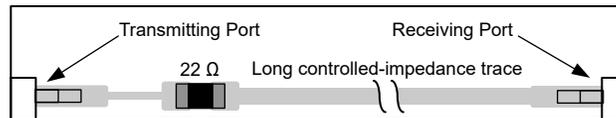
**Figure 8-3. Example Bypass Capacitor Placement for TSSOP and Similar Packages**



**Figure 8-4. Example Bypass Capacitor Placement for WQFN and Similar Packages**



**Figure 8-5. Example Bypass Capacitor Placement for SOT, SC70 and Similar Packages**



**Figure 8-6. Example Damping Resistor Placement for Improved Signal Integrity**

## 9 Device and Documentation Support

TI offers an extensive line of development tools. Tools and software to evaluate the performance of the device, generate code, and develop solutions are listed below.

### 9.1 Documentation Support

#### 9.1.1 Related Documentation

For related documentation, see the following:

- Texas Instruments, [CMOS Power Consumption and  \$C\_{pd}\$  Calculation application report](#)
- Texas Instruments, [Designing With Logic application report](#)
- Texas Instruments, [Thermal Characteristics of Standard Linear and Logic \(SLL\) Packages and Devices application report](#)

### 9.2 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on [ti.com](http://ti.com). Click on *Notifications* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

### 9.3 Support Resources

[TI E2E™ support forums](#) are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

Linked content is provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

### 9.4 Trademarks

NanoStar™ is a trademark of Texas Instruments.

TI E2E™ is a trademark of Texas Instruments.

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### 9.5 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

### 9.6 Glossary

[TI Glossary](#) This glossary lists and explains terms, acronyms, and definitions.

## 10 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

<b>Changes from Revision C (February 2012) to Revision D (June 2025)</b>	<b>Page</b>
• Added <i>Package Information</i> table, <i>Pin Functions</i> table, <i>ESD Ratings</i> table, <i>Thermal Information</i> table, <i>Device Functional Modes</i> , Application and Implementation section, <i>Device and Documentation Support</i> section, and <i>Mechanical, Packaging, and Orderable Information</i> section .....	1
• Updated operating temperature to 125°C and respective values in <i>Electrical Characteristics</i> table, <i>Recommended Operating Conditions</i> table, and <i>Switching Characteristics</i> tables.....	1

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**Changes from Revision B (March 2012) to Revision C (February 2012)**

**Page**

- Updated ORDERING INFORMATION table. .... 1
- 

**11 Mechanical, Packaging, and Orderable Information**

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

**PACKAGING INFORMATION**

Orderable part number	Status (1)	Material type (2)	Package   Pins	Package qty   Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
<a href="#">SN74AUP2G14DCKR</a>	Active	Production	SC70 (DCK)   6	3000   LARGE T&R	Yes	NIPDAU   SN	Level-1-260C-UNLIM	-40 to 125	(H65, H6F)
SN74AUP2G14DCKR.B	Active	Production	SC70 (DCK)   6	3000   LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 85	(H65, H6F)
<a href="#">SN74AUP2G14DCKRG4</a>	Active	Production	SC70 (DCK)   6	3000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	(H65, H6F)
SN74AUP2G14DCKRG4.B	Active	Production	SC70 (DCK)   6	3000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	(H65, H6F)
<a href="#">SN74AUP2G14DRYR</a>	Active	Production	SON (DRY)   6	5000   LARGE T&R	Yes	NIPDAU   NIPDAUAG	Level-1-260C-UNLIM	-40 to 85	H6
SN74AUP2G14DRYR.B	Active	Production	SON (DRY)   6	5000   LARGE T&R	Yes	NIPDAUAG	Level-1-260C-UNLIM	-40 to 85	H6
<a href="#">SN74AUP2G14DRYRG4</a>	Active	Production	SON (DRY)   6	5000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	H6
SN74AUP2G14DRYRG4.B	Active	Production	SON (DRY)   6	5000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	H6
<a href="#">SN74AUP2G14DSF2</a>	Active	Production	SON (DSF)   6	5000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	H6
SN74AUP2G14DSF2.B	Active	Production	SON (DSF)   6	5000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	H6
<a href="#">SN74AUP2G14DSFR</a>	Active	Production	SON (DSF)   6	5000   LARGE T&R	Yes	NIPDAU   NIPDAUAG	Level-1-260C-UNLIM	-40 to 85	H6
SN74AUP2G14DSFR.B	Active	Production	SON (DSF)   6	5000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	H6
<a href="#">SN74AUP2G14DSFRG4</a>	Active	Production	SON (DSF)   6	5000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	H6
SN74AUP2G14DSFRG4.B	Active	Production	SON (DSF)   6	5000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	H6
<a href="#">SN74AUP2G14YFPR</a>	Active	Production	DSBGA (YFP)   6	3000   LARGE T&R	Yes	SNAGCU	Level-1-260C-UNLIM	-40 to 85	HFN
SN74AUP2G14YFPR.B	Active	Production	DSBGA (YFP)   6	3000   LARGE T&R	Yes	SNAGCU	Level-1-260C-UNLIM	-40 to 85	HFN

(1) **Status:** For more details on status, see our [product life cycle](#).

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

**(6) Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "-" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

**TAPE AND REEL INFORMATION**

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


\*All dimensions are nominal

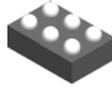
Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AUP2G14DCKR	SC70	DCK	6	3000	178.0	8.4	2.25	2.45	1.2	4.0	8.0	Q3
SN74AUP2G14DCKRG4	SC70	DCK	6	3000	178.0	9.0	2.4	2.5	1.2	4.0	8.0	Q3
SN74AUP2G14DCKRG4	SC70	DCK	6	3000	178.0	9.2	2.4	2.4	1.22	4.0	8.0	Q3
SN74AUP2G14DRYR	SON	DRY	6	5000	180.0	9.5	1.15	1.6	0.75	4.0	8.0	Q1
SN74AUP2G14DRYRG4	SON	DRY	6	5000	180.0	9.5	1.15	1.6	0.75	4.0	8.0	Q1
SN74AUP2G14DSF2	SON	DSF	6	5000	180.0	8.4	1.16	1.16	0.5	4.0	8.0	Q3
SN74AUP2G14DSFR	SON	DSF	6	5000	180.0	8.4	1.16	1.16	0.5	4.0	8.0	Q2
SN74AUP2G14DSFRG4	SON	DSF	6	5000	180.0	8.4	1.16	1.16	0.5	4.0	8.0	Q2
SN74AUP2G14YFPR	DSBGA	YFP	6	3000	178.0	9.2	0.89	1.29	0.62	4.0	8.0	Q1

**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AUP2G14DCKR	SC70	DCK	6	3000	208.0	191.0	35.0
SN74AUP2G14DCKRG4	SC70	DCK	6	3000	180.0	180.0	18.0
SN74AUP2G14DCKRG4	SC70	DCK	6	3000	180.0	180.0	18.0
SN74AUP2G14DRYR	SON	DRY	6	5000	184.0	184.0	19.0
SN74AUP2G14DRYRG4	SON	DRY	6	5000	184.0	184.0	19.0
SN74AUP2G14DSF2	SON	DSF	6	5000	210.0	185.0	35.0
SN74AUP2G14DSFR	SON	DSF	6	5000	210.0	185.0	35.0
SN74AUP2G14DSFRG4	SON	DSF	6	5000	210.0	185.0	35.0
SN74AUP2G14YFPR	DSBGA	YFP	6	3000	220.0	220.0	35.0

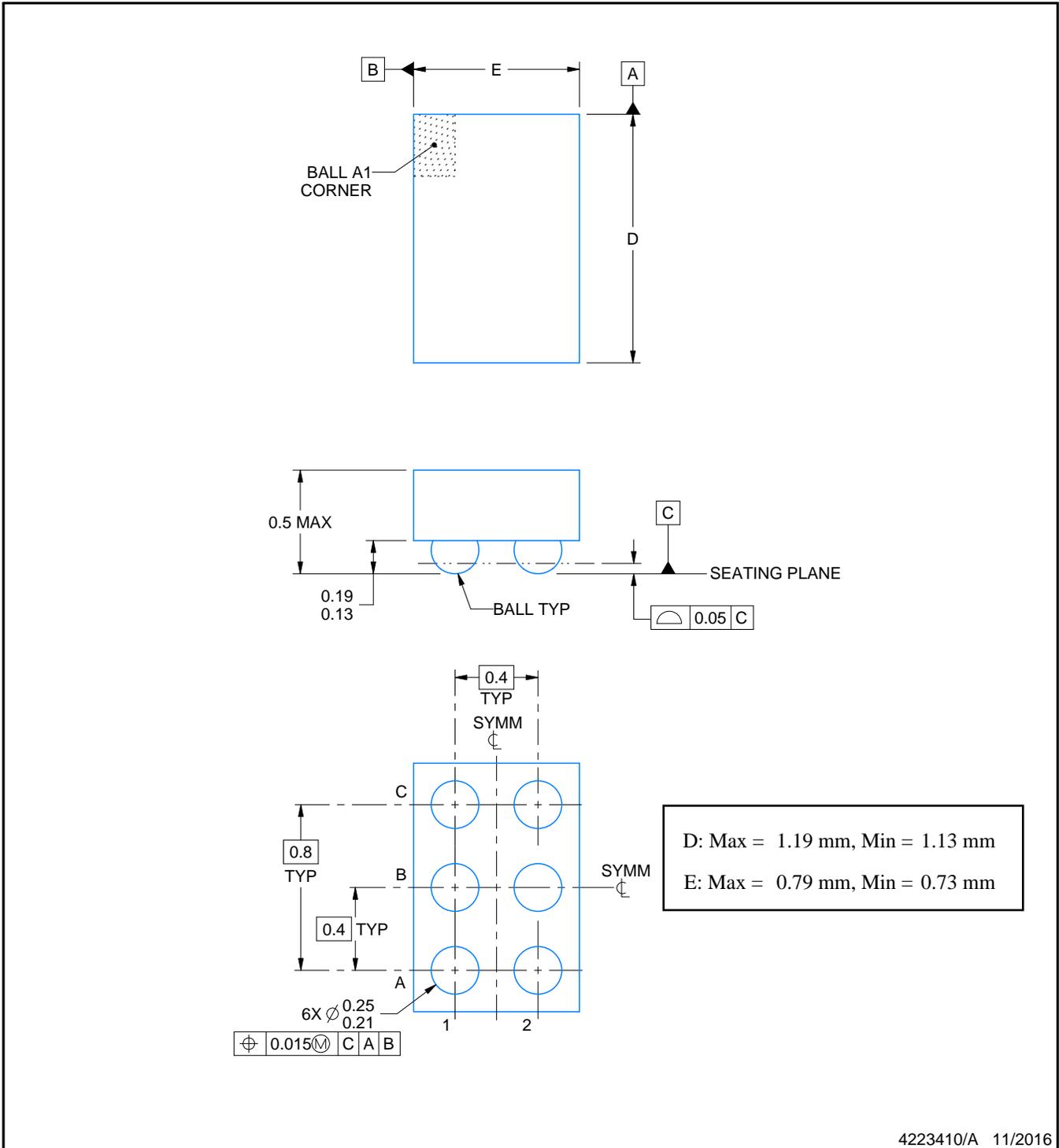
YFP0006



# PACKAGE OUTLINE

DSBGA - 0.5 mm max height

DIE SIZE BALL GRID ARRAY



4223410/A 11/2016

NOTES:

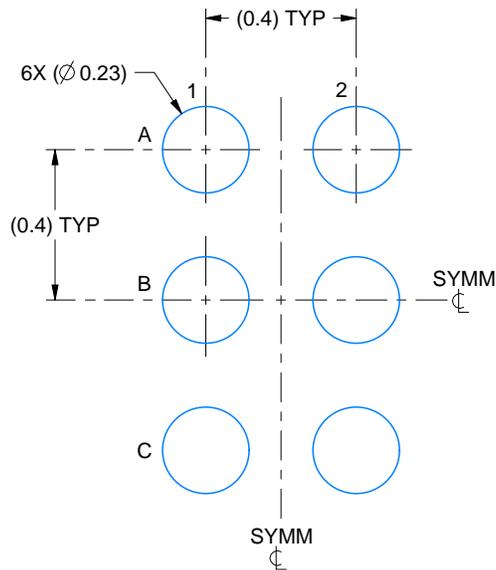
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.

# EXAMPLE BOARD LAYOUT

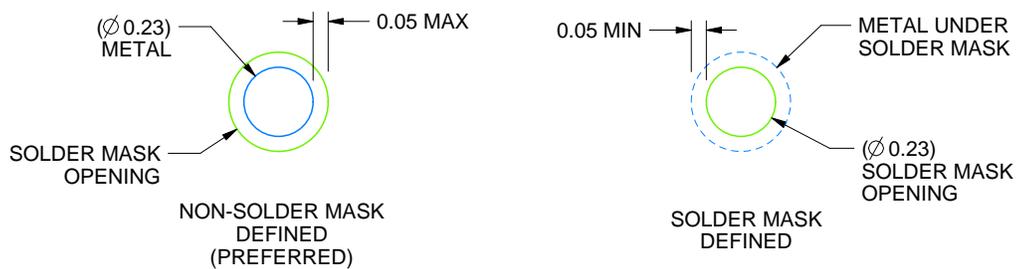
YFP0006

DSBGA - 0.5 mm max height

DIE SIZE BALL GRID ARRAY



LAND PATTERN EXAMPLE  
SCALE:50X



SOLDER MASK DETAILS  
NOT TO SCALE

4223410/A 11/2016

NOTES: (continued)

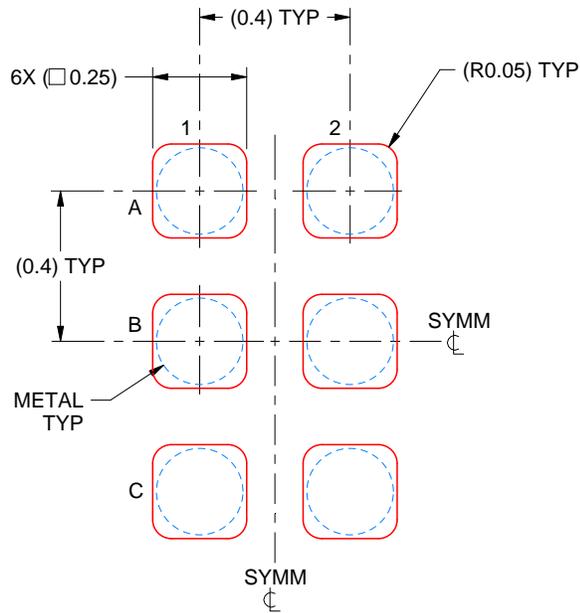
- Final dimensions may vary due to manufacturing tolerance considerations and also routing constraints. For more information, see Texas Instruments literature number SNVA009 ([www.ti.com/lit/snva009](http://www.ti.com/lit/snva009)).

# EXAMPLE STENCIL DESIGN

YFP0006

DSBGA - 0.5 mm max height

DIE SIZE BALL GRID ARRAY



SOLDER PASTE EXAMPLE  
BASED ON 0.1 mm THICK STENCIL  
SCALE:50X

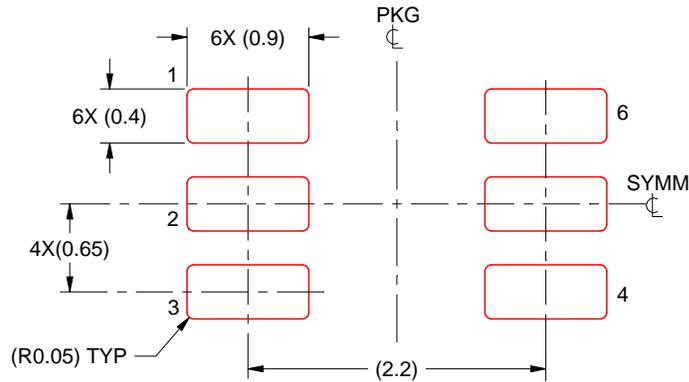
4223410/A 11/2016

NOTES: (continued)

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release.







SOLDER PASTE EXAMPLE  
BASED ON 0.125 THICK STENCIL  
SCALE:18X

4214835/D 11/2024

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

## GENERIC PACKAGE VIEW

**DRY 6**

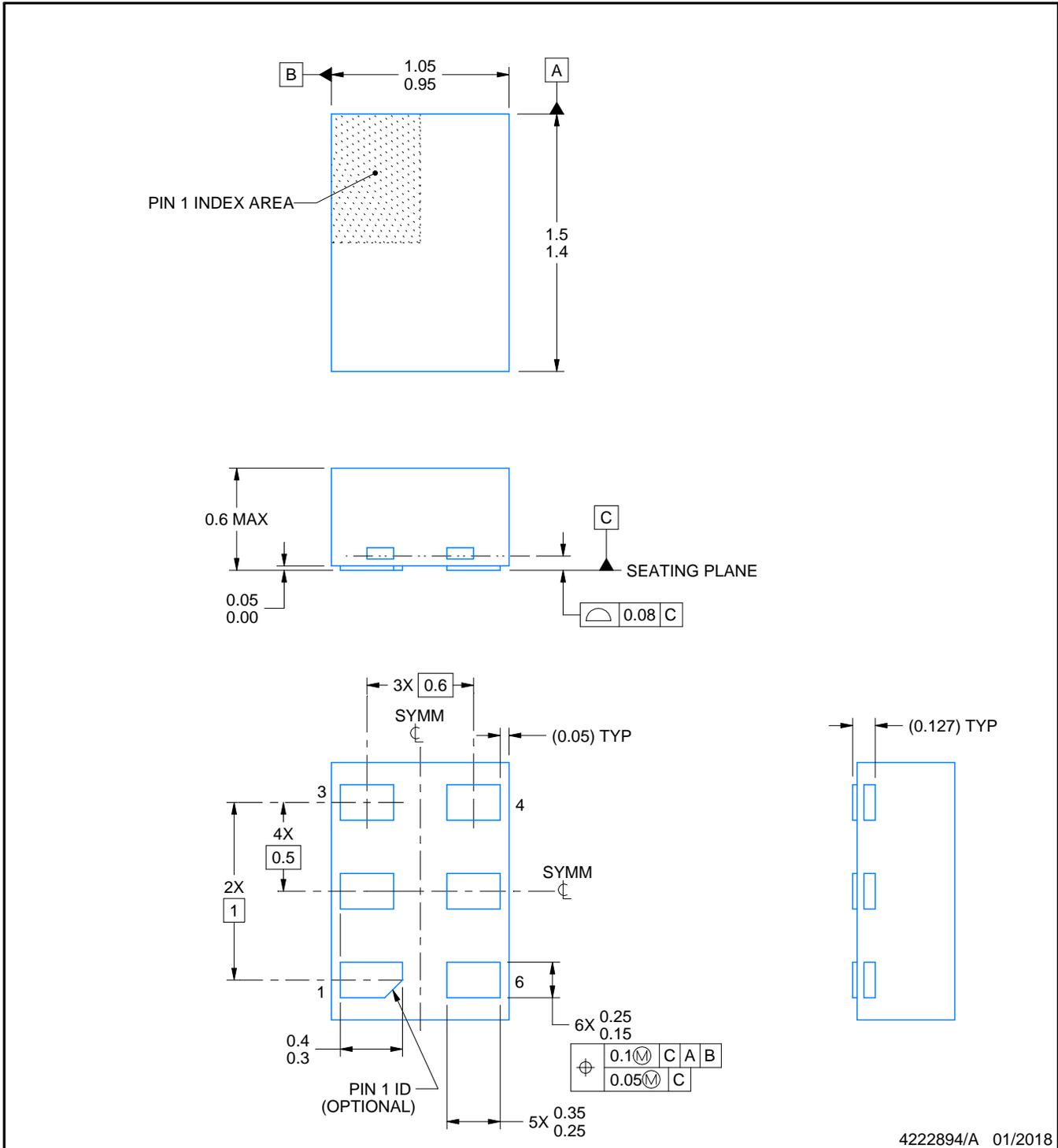
**USON - 0.6 mm max height**

PLASTIC SMALL OUTLINE - NO LEAD



Images above are just a representation of the package family, actual package may vary.  
Refer to the product data sheet for package details.

4207181/G



4222894/A 01/2018

NOTES:

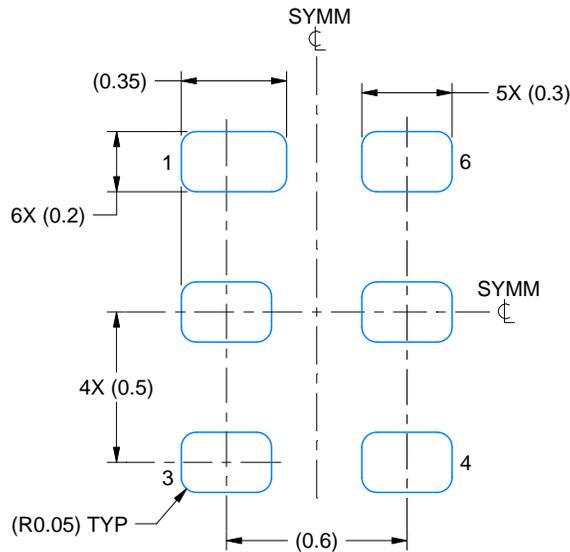
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.

# EXAMPLE BOARD LAYOUT

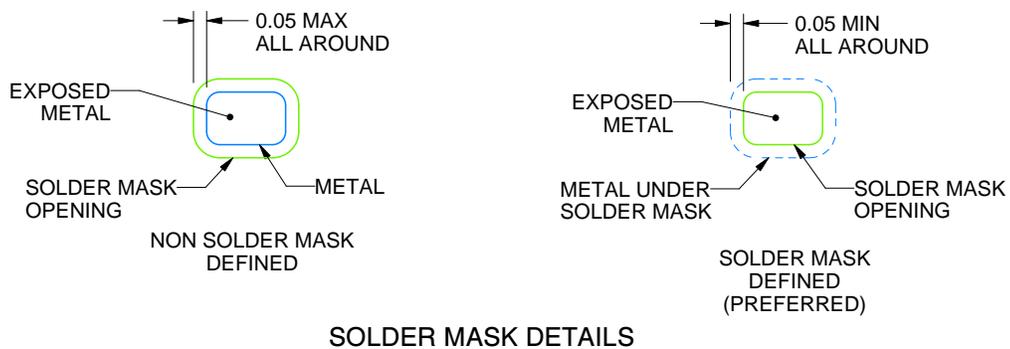
DRY0006A

USON - 0.6 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



**LAND PATTERN EXAMPLE**  
 1:1 RATIO WITH PKG SOLDER PADS  
 EXPOSED METAL SHOWN  
 SCALE:40X



**SOLDER MASK DETAILS**

4222894/A 01/2018

NOTES: (continued)

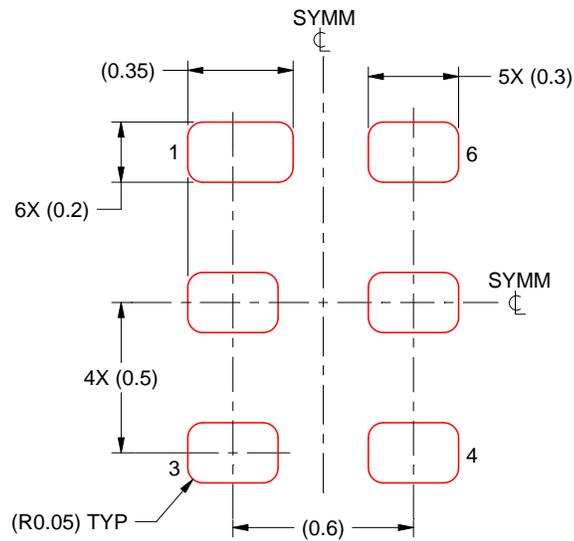
3. For more information, see QFN/SON PCB application report in literature No. SLUA271 ([www.ti.com/lit/slue271](http://www.ti.com/lit/slue271)).

# EXAMPLE STENCIL DESIGN

DRY0006A

USON - 0.6 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



SOLDER PASTE EXAMPLE  
BASED ON 0.075 - 0.1 mm THICK STENCIL  
SCALE:40X

4222894/A 01/2018

NOTES: (continued)

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

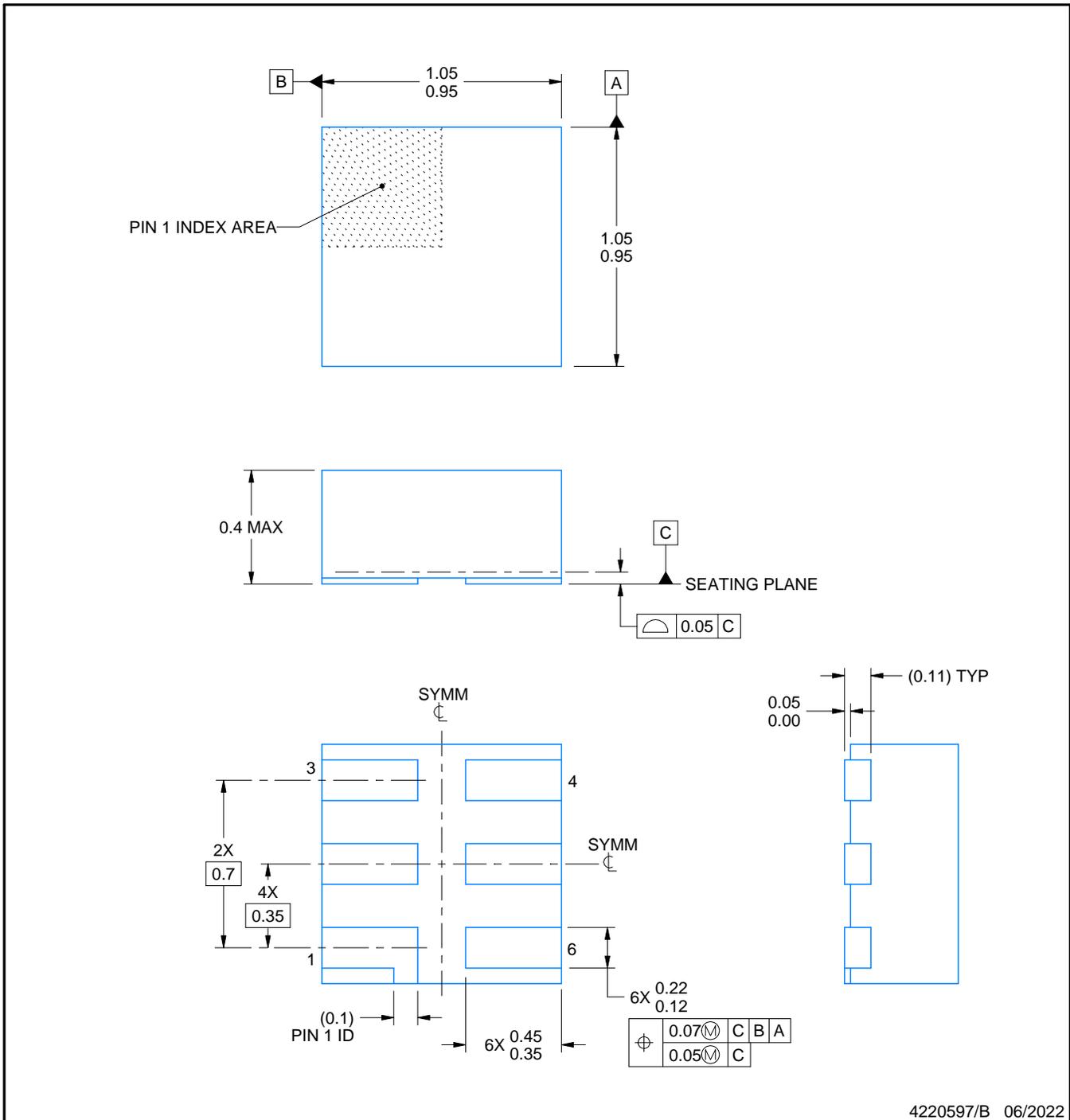


**DSF0006A**

**PACKAGE OUTLINE**

**X2SON - 0.4 mm max height**

PLASTIC SMALL OUTLINE - NO LEAD



**NOTES:**

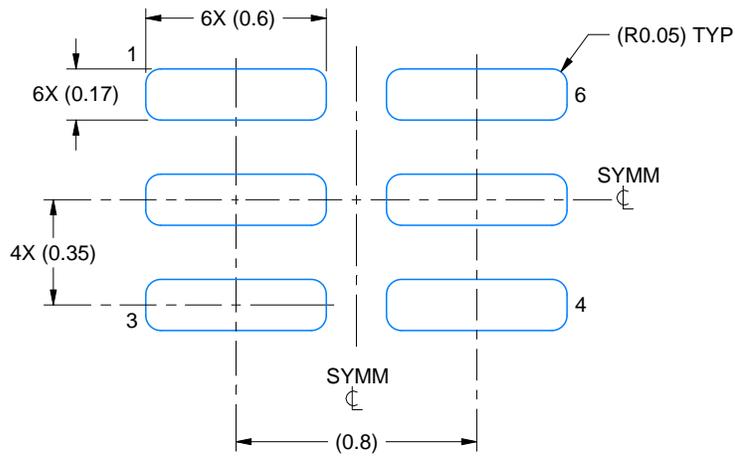
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Reference JEDEC registration MO-287, variation X2AAF.

# EXAMPLE BOARD LAYOUT

DSF0006A

X2SON - 0.4 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE:40X



SOLDER MASK DETAILS

4220597/B 06/2022

NOTES: (continued)

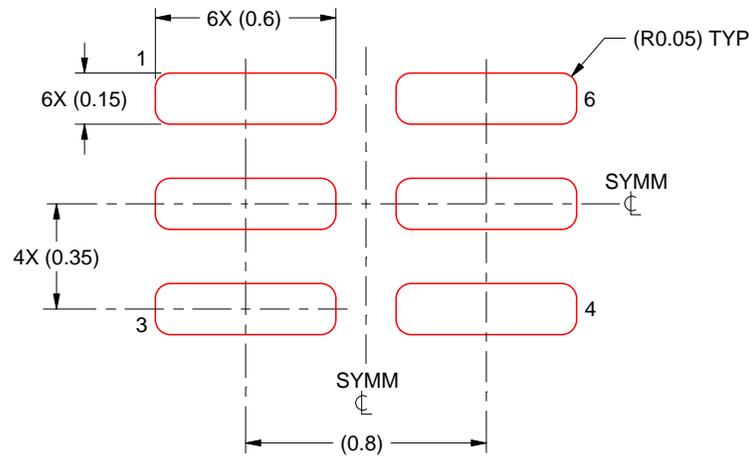
4. For more information, see Texas Instruments literature number SLUA271 ([www.ti.com/lit/slua271](http://www.ti.com/lit/slua271)).

# EXAMPLE STENCIL DESIGN

DSF0006A

X2SON - 0.4 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



SOLDER PASTE EXAMPLE  
BASED ON 0.09 mm THICK STENCIL

PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE  
SCALE:40X

4220597/B 06/2022

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

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